

AOL1400
N-Channel Enhancement Mode Field Effect Transistor

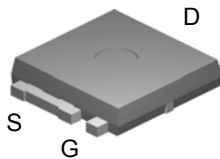
General Description

The AOL1400 uses advanced trench technology to provide excellent $R_{DS(ON)}$, shoot-through immunity and good body diode characteristics. This device is ideally suited for use as a low side switch in CPU core power conversion. *Standard product AOL1400 is Pb-free (meets ROHS & Sony 259 specifications). AOL1400L is a Green Product ordering option. AOL1400 and AOL1400L are electrically identical.*

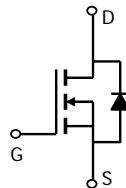
Features

$V_{DS} (V) = 30V$
 $I_D = 85A \quad (V_{GS} = 10V)$
 $R_{DS(ON)} < 4.5m\Omega (V_{GS} = 10V)$
 $R_{DS(ON)} < 5.5m\Omega (V_{GS} = 4.5V)$

Ultra SO-8™ Top View


Fits SOIC8 footprint !

Bottom tab connected to drain


Absolute Maximum Ratings $T_A=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current ^B	I_D	$T_C=25^\circ C^G$	85
		$T_C=100^\circ C^B$	70
Pulsed Drain Current	I_{DM}	200	A
Continuous Drain Current ^G	I_{DSM}	$T_A=25^\circ C$	17
		$T_A=70^\circ C$	13
Avalanche Current ^C	I_{AR}	30	A
Repetitive avalanche energy $L=0.3mH^C$	E_{AR}	145	mJ
Power Dissipation ^B	P_D	$T_C=25^\circ C$	100
		$T_C=100^\circ C$	50
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ C$	2.1
		$T_A=70^\circ C$	1.3
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	21	25	$^\circ C/W$
$t \leq 10s$				
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	48	60	$^\circ C/W$
Steady-State				
Maximum Junction-to-Case ^C	$R_{\theta JC}$	1	1.5	$^\circ C/W$

AOL1400

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V T _J =55°C		0.005	1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±12V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	0.6	1.1	1.8	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	100			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A T _J =125°C		3.9	4.5	mΩ
		V _{GS} =4.5V, I _D =20A		5	6	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		102		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.64	1	V
I _S	Maximum Body-Diode Continuous Current				85	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		9130	10500	pF
C _{oss}	Output Capacitance			625		pF
C _{rss}	Reverse Transfer Capacitance			387		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		0.4	0.8	Ω
SWITCHING PARAMETERS						
Q _{g(4.5V)}	Total Gate Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =20A		72.4	85	nC
Q _{gs}	Gate Source Charge			13.4		nC
Q _{gd}	Gate Drain Charge			16.8		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =0.75Ω, R _{GEN} =3Ω		14.7	22	ns
t _r	Turn-On Rise Time			14.2	21	ns
t _{D(off)}	Turn-Off DelayTime			105.5	150	ns
t _f	Turn-Off Fall Time			23.5	35	ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =20A, dI/dt=100A/μs		30.5	40	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, dI/dt=100A/μs		21	33	nC

A: The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation P_{DSM} is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.

B: The power dissipation P_D is based on T_{J(MAX)}=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=175°C.

D: The R_{θJA} is the sum of the thermal impedance from junction to case R_{θJC} and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T_{J(MAX)}=175°C.

G: The maximum current rating is limited by bond-wires.

H: These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_J=25°C.

Rev 1: Dec 2005

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

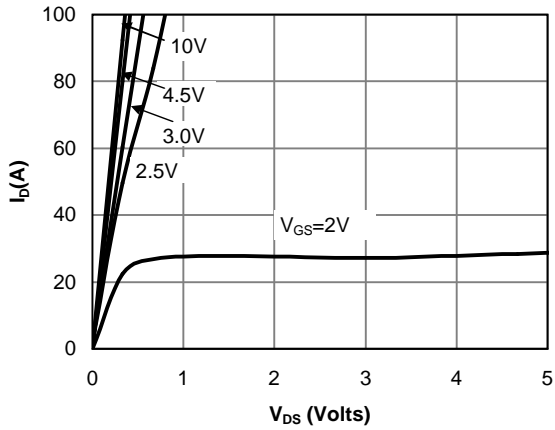


Figure 1: On-Region Characteristics

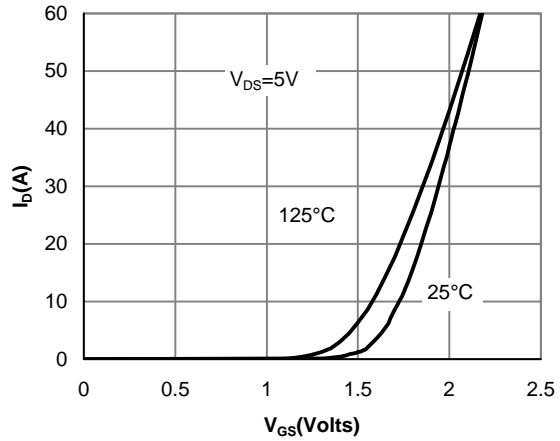


Figure 2: Transfer Characteristics

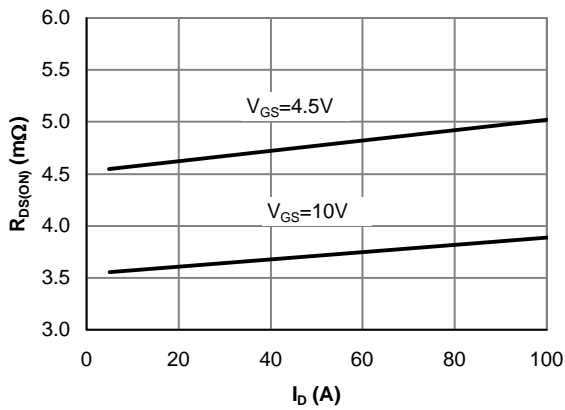


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

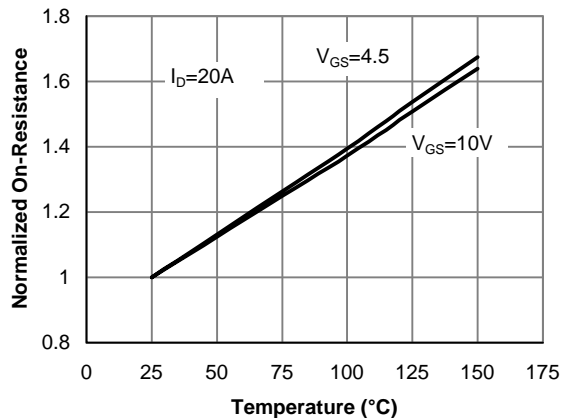


Figure 4: On-Resistance vs. Junction Temperature

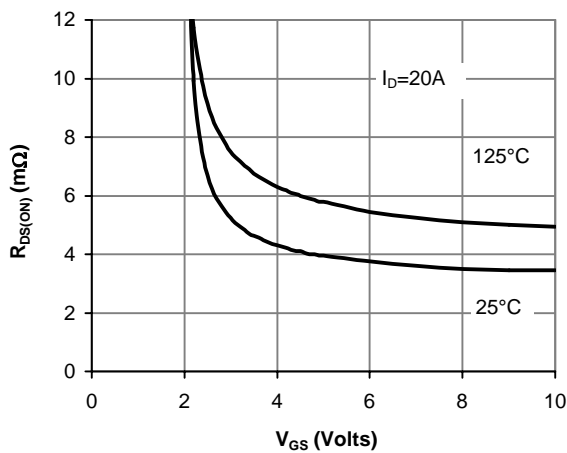


Figure 5: On-Resistance vs. Gate-Source Voltage

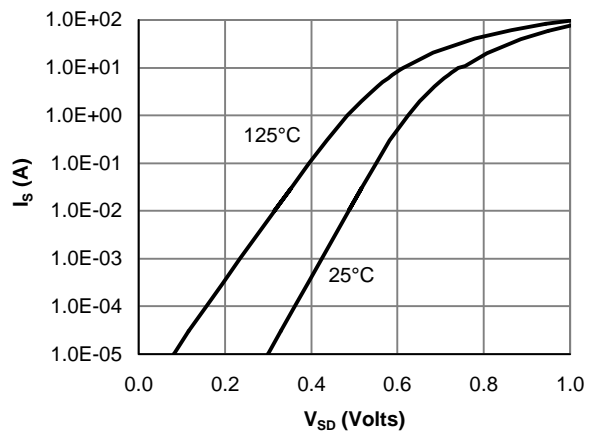


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

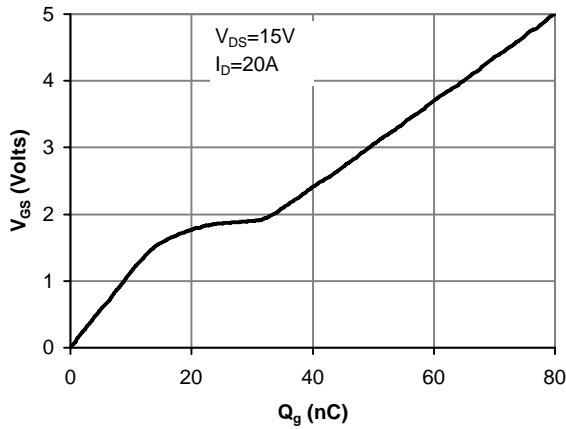


Figure 7: Gate-Charge Characteristics

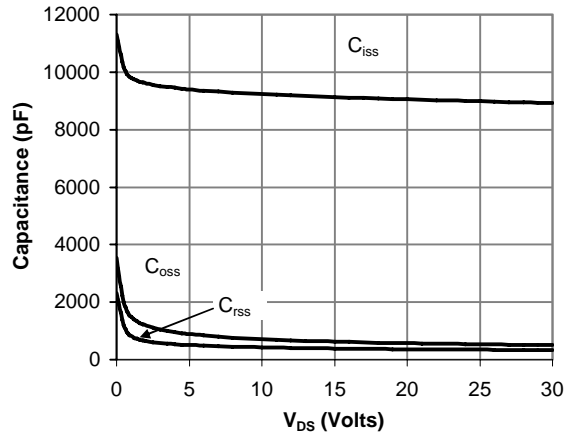


Figure 8: Capacitance Characteristics

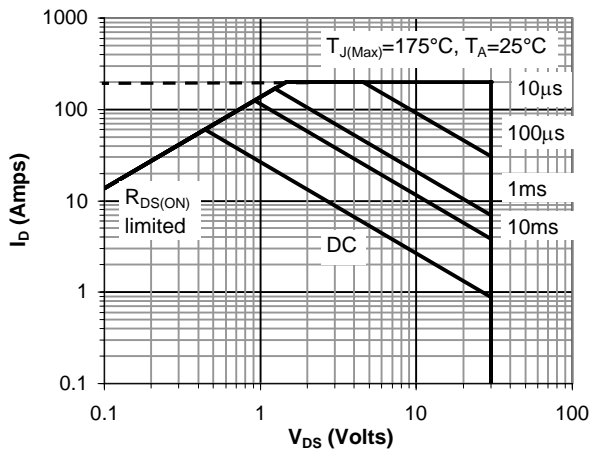


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

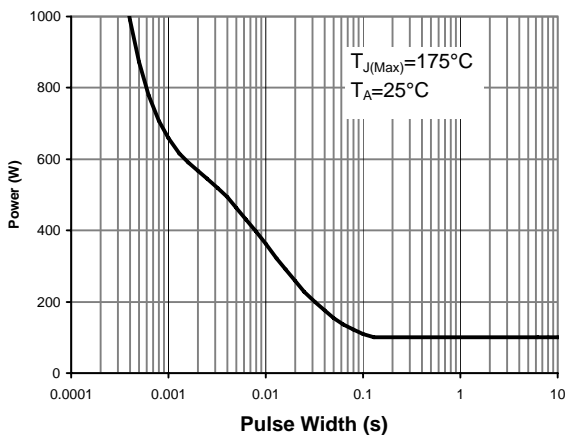


Figure 10: Single Pulse Power Rating Junction-to-Case (Note B)

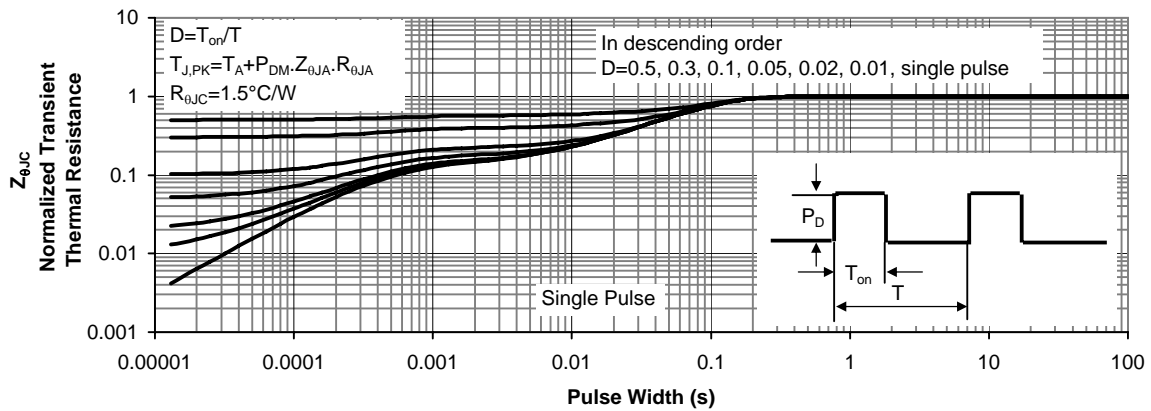


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

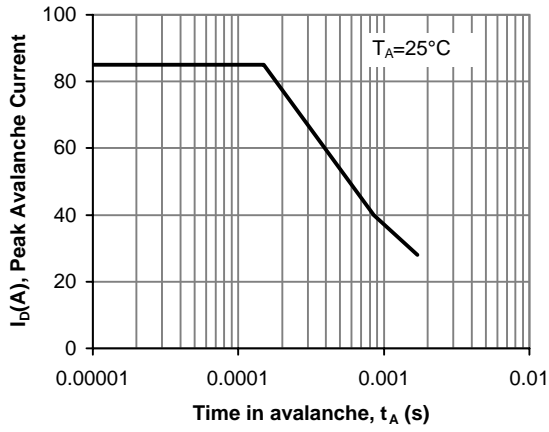


Figure 12: Single Pulse Avalanche capability

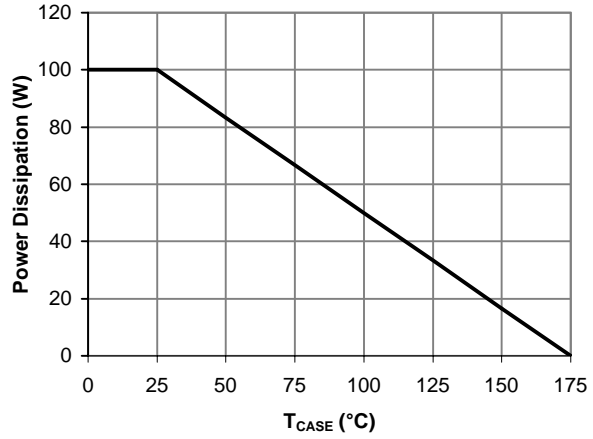


Figure 13: Power De-rating (Note B)

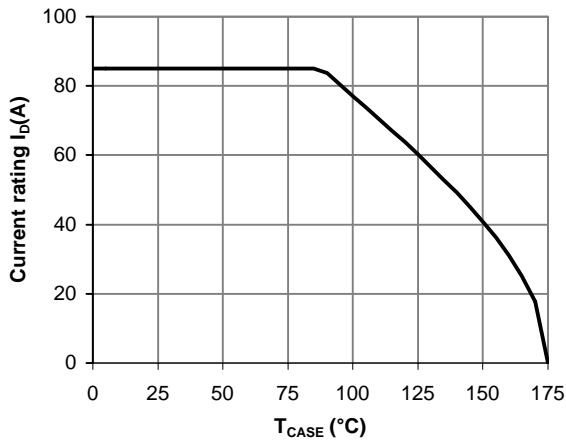


Figure 14: Current De-rating (Note B)

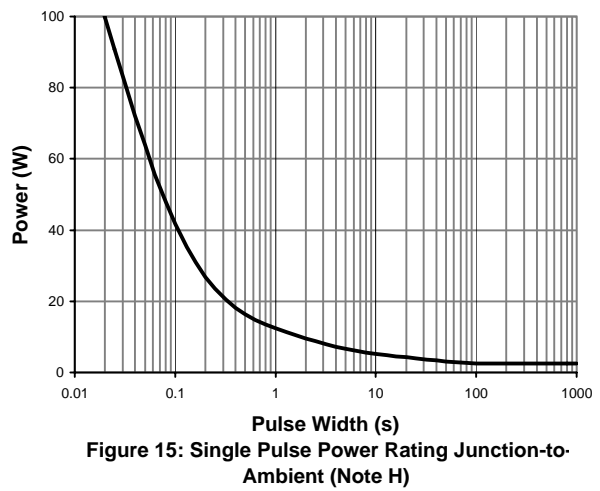


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

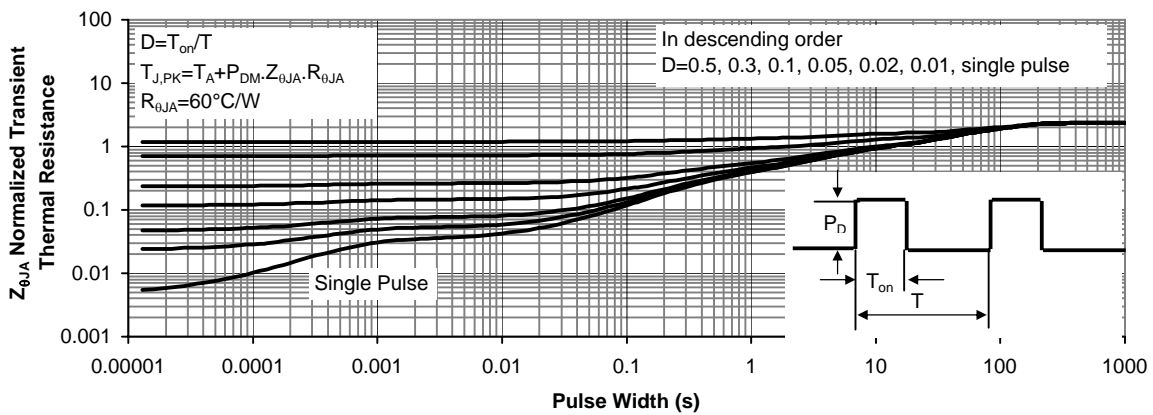


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)